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Part Number: [0877612400](#)
Status: **Active**
Overview: [milligrid](#)
Description: 2.00mm (.079") Pitch Milli-Grid™ Header, Dual Row Dual Body, Through Hole, Vertical, 24 Circuits, 0.75µm (30µ") Gold (Au) Selective Plating, 27.50mm (1.083") Stacking Height, Tray Packaging, Lead-free

Documents:
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)
[Product Specification PS-87761-100 \(PDF\)](#)

General
Product Family PCB Headers
Series [87761](#)
Application Board-to-Board
Overview [milligrid](#)
Product Name Dual Body, Milli-Grid™

Physical
Breakaway Yes
Circuits (Loaded) 24
Circuits (maximum) 24
Color - Resin Black
First Mate / Last Break No
Glow-Wire Compliant No
Guide to Mating Part No
Keying to Mating Part None
Lock to Mating Part None
Mated Height (in) 0.217 In
Mated Height (mm) 5.50 mm
Material - Metal Copper Alloy
Material - Plating Mating Gold
Material - Plating Termination Tin
Material - Resin Nylon
Number of Rows 2
Orientation Vertical
PCB Locator No
PCB Retention None
Packaging Type Tray
Pitch - Mating Interface (in) 0.079 In
Pitch - Mating Interface (mm) 2.00 mm
Pitch - Term. Interface (in) 0.079 In
Pitch - Term. Interface (mm) 2.00 mm
Plating min: Mating (µin) 30
Plating min: Mating (µm) 0.75
Plating min: Termination (µin) 79
Plating min: Termination (µm) 2.00
Polarized to Mating Part No
Polarized to PCB No
Robotic Placement None
Shrouded No
Stackable No
Temperature Range - Operating -55°C to +105°C
Termination Interface: Style Through Hole

Electrical

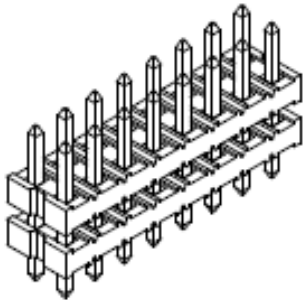


image - Reference only

Series

EU RoHS
ELV and RoHS
Compliant
REACH SVHC
Contains SVHC: No
Halogen-Free
Status

China RoHS



Need more information on product environmental compliance?
Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)
Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
[87761Series](#)

Mates With
[79109](#) Board-to-Board Top/Bottom Entry SMT Receptacle

Current - Maximum per Contact	2A
Voltage - Maximum	125V

Material Info

Reference - Drawing Numbers

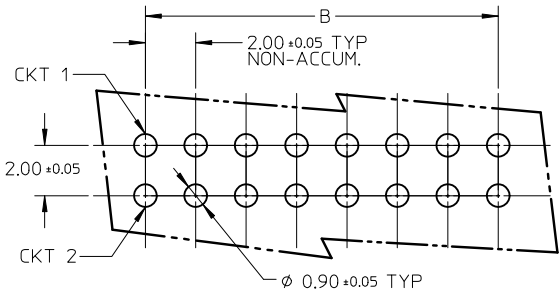
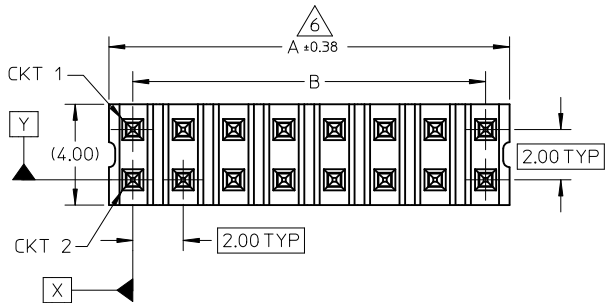
Product Specification	PS-87761-100
Sales Drawing	SD-87761-052

This document was generated on 05/26/2010

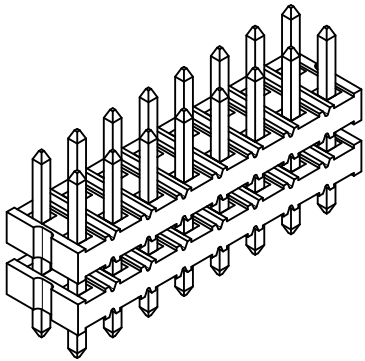
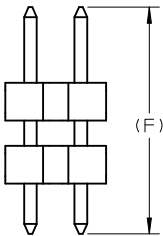
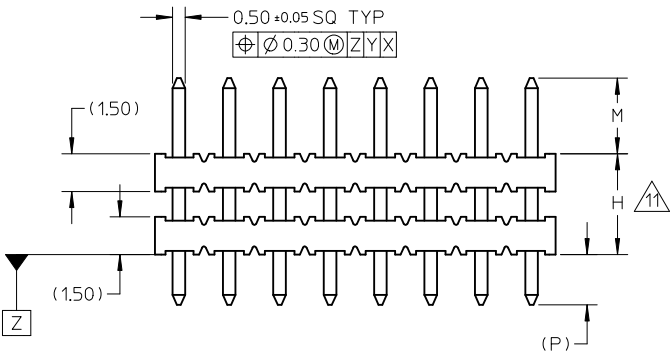
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10 9 8 7 6 5 4 3 2 1

- NOTES:
- MATERIAL:
HSG: NYLON, GLASS-FILLED, UL94V-0 COLOR: BLACK
PIN: 0.50MM SQ, COPPER ALLOY
 - PLATING FINISH:
 - 0.38µm MIN. GOLD OVER
1.25µm MIN. NICKEL OVERALL.
 - GOLD FLASH ON CONTACT AND
2.50µm MIN. TIN ON SOLDER TAIL OVER
1.25µm MIN. NICKEL OVERALL.
 - 0.38µm MIN. GOLD PLATE ON CONTACT AND
2.00µm MIN. TIN ON SOLDER TAIL OVER
1.25µm MIN. NICKEL OVERALL.
 - 0.75µm MIN. GOLD PLATE ON CONTACT AND
2.00µm MIN. TIN ON SOLDER TAIL OVER
1.25µm MIN. NICKEL OVERALL.
 - 2.50µm MIN. TIN OVERALL
1.25µm MIN. NICKEL OVERALL.
 - 0.38µm MIN. GOLD PLATE ON CONTACT AND
0.05µm MIN. GOLD ON SOLDER TAIL OVER
1.25µm MIN. NICKEL OVERALL.
 - 0.75µm MIN. GOLD PLATE ON CONTACT AND
0.05µm MIN. GOLD ON SOLDER TAIL OVER
1.25µm MIN. NICKEL OVERALL.
 - 0.75µm MIN. GOLD OVERALL
1.25µm MIN. NICKEL OVERALL.
 - PIN PUSHOUT FORCE: 0.85KgF MIN IN EITHER DIRECTION.
 - THE ABOVE 16CKTS SHOWN IS FOR ILLUSTRATION ONLY.
 - FOR PACKING OPTION PLEASE REFER TO THE TABLE.
 - IRREGULAR CIRCUIT CUTOFF WITHIN BREAKAWAY SECTION IS PERMISSIBLE. CUTTING OR CHIPPING OF THE MAIN BODY IS NOT ACCEPTABLE
 - PRODUCT SPEC PS-87761-001 APPLIES.
 - RECOMMENDED PCB THICKNESS 1.60MM.
 - WAFER TO BE FLAT WITHIN 0.003 mm/mm
 - PACKAGING SPECIFICATION:
TRAY: PK-89990-487
BULK: PK-89990-490
TUBE: PK-89990-475
 - WHEN WAFER ARE STACK TOGETHER, DIMENSION 'H' SHOULD BE TAKEN AS REFERENCE.



RECOMMENDED P.C.B HOLE LAYOUT



0087-DW-FUJITSU EC NO: S2010-0896 DRWN:SKANG CHKD:ATSEE APPR:MLONG 2010/04/23 2010/05/24 2010/05/29	DESCRIPTION REV	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
				mm	INCH	DRAWN BY	DATE	TITLE 2MM DUAL ROW DUAL WAFER HEADER, VERTICAL T/H				
			4 PLACES	± ---	± ---	KCHO	2005/02/23					
			3 PLACES	± ---	± ---	CHECKED BY	DATE	MOLEX INCORPORATED				
			2 PLACES	± 0.20	± ---	PTLIM	2005/04/26					
			1 PLACE	± ---	± ---	APPROVED BY	DATE	SD-87761-052				
			ANGULAR ± 3 °		MLONG	2009/12/02						
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		DOCUMENT NO.		SHEET NO.			
					SEE TABLE				1 OF 3			
					THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

9 8 7 6 5 4 3 2 1

[illegible]

10		9		8		7		6		5		4		3		2		1	
PART NUMBERS		CKT SIZE	VOID POSITION	KINK POSITION	DIMENSION				PLATING OPTION	PACKAGING TYPE									
					MATING END	STACKER HEIGHT	SOLDER TAIL	(F)											
					M	H	(P)												
87761-5001		50	----	----	2.50	10.30	4.00	16.80	4	TRAY									
12 87761-5021		50	----	----	4.00	8.70	2.50	15.20	3										
12 87761-5022		50	----	----	4.00	5.71	2.50	12.21	3										

0087-DW-FUJITSU
EC NO: S2010-0896
DRWN:SKANG 2010/04/23
CHKD:ATSEE 2010/05/24
APPR:MLONG 2010/05/29

DESCRIPTION
REV

QUALITY SYMBOLS
▽=0
◻=0

GENERAL TOLERANCES (UNLESS SPECIFIED)
mm INCH
4 PLACES ± --- ± ---
3 PLACES ± --- ± ---
2 PLACES ± 0.20 ± ---
1 PLACE ± --- ± ---
ANGULAR ± 3 °
DRAFT WHERE APPLICABLE
MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE
MM ONLY
DRAWN BY DATE
KCHO 2005/02/23
CHECKED BY DATE
PTL IM 2005/04/26
APPROVED BY DATE
MLONG 2009/12/02
MATERIAL NO.
SEE TABLE

SCALE
NTS
DESIGN UNITS
METRIC
THIRD ANGLE PROJECTION
TITLE
2MM DUAL ROW DUAL WAFER
HEADER, VERTICAL T/H
MOLEX INCORPORATED
DOCUMENT NO.
SD-87761-052
SHEET NO.
3 OF 3